(19) Europäisches Patentamt
European Patent Office
Office européen des brevets

(11) EP 0 987 748 A3

(12) EUROPEAN PATENT APPLICATION

(88) Date of publication A3:
11.05.2005 Bulletin 2005/19

(43) Date of publication A2:
22.03.2000 Bulletin 2000/12

(21) Application number: **99118391.4**

(22) Date of filing: **16.09.1999**

(51) Int Cl.[7]: **H01L 21/48**, H01L 23/538

(84) Designated Contracting States:
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE
Designated Extension States:
AL LT LV MK RO SI

(30) Priority: **18.09.1998 JP 26441098**

(71) Applicants:
- **NEC Compound Semiconductor Devices, Ltd.**
  Kawasaki, Kanagawa 211-8666 (JP)
- **Fuchigami Micro Co.,Ltd.**
  Kagoshima-shi, Kagoshima (JP)

(72) Inventors:
- **Hirasawa, Koki.**
  Minato-ku, Tokyo (JP)
- **Ono, Teruo**
  Kiire-cho, Ibusuki-gun, Kagoshima (JP)

(74) Representative: **Glawe, Delfs, Moll & Partner**
Patentanwälte
Postfach 26 01 62
80058 München (DE)

(54) **Multilayered circuit board for semiconductor chip module, and method of manufacturing the same**

(57) A multilayered circuit board for a semiconductor chip module includes an underlying board, insulating layers, fixed-potential wiring layers, via holes, and metal layers. The underlying board has a major surface made of a metal material to which a fixed potential is applied. The insulating layers are stacked on the major surface of the underlying board and have wiring layers formed on their surfaces. The fixed-potential wiring layers constitute part of the wiring layers formed on the insulating layers. The via holes are formed below the fixed-potential wiring layers to extend through the insulating layers. The metal layers are filled in the via holes so as to make upper ends be connected to the lower surfaces of the fixed-potential wiring layers. One of the insulating layers in contact with the major surface of the underlying board is formed on the underlying board while the lower end of the metal layer is in contact with the major surface of the underlying board. The other insulating layer formed on the insulating layer in contact with the major surface of the underlying board is stacked while the lower end of the metal layer is in contact with the upper surface of the fixed-potential wiring layer of one insulating layer.

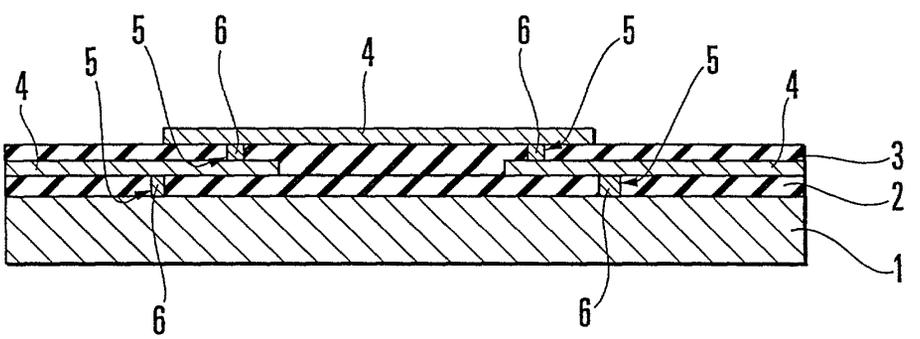

FIG. 1

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EUROPEAN SEARCH REPORT

Application Number
EP 99 11 8391

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TECHNICAL FIELDS SEARCHED (Int.Cl.7)
H05K H01L

The present search report has been drawn up for all claims

Place of search	Date of completion of the search	Examiner
Berlin	17 March 2005	Morena, E

CATEGORY OF CITED DOCUMENTS

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EPO FORM 1503 03.82 (P04C01)

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